

TPS65261EVM-650 PMIC 3-A, 2-A, 2-A Output Current Evaluation Module

This document presents the information required to operate the TPS65261 PMIC as well as the support documentation including schematic, layout, hardware setup, and bill of materials (BOM).

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1 Background

The TPS65261 PMIC is a triple 3-A, 2-A, 2-A output current, synchronous step-down (buck) converter with an operational range of 4.5 V to 18 V. The TPS65261 features an automatic power sequence with connecting MODE pin to V7V and configuring EN1/2/3 pins. The device also features an open drain RESET signal to monitor power down. The TPS65261 operates in pulse skipping mode (PSM) light load.

As there are many possible options to set the converters, [Table 1](#) presents the performance specification summary for the EVM.

Table 1. Summary of Performance

Test Conditions	Performance
VIN = 4.5 V to 18 V f _{SW} = 600 kHz (25°C ambient)	BUCK1, 1.2 V, up to 3 A BUCK2, 3.3 V, up to 2 A BUCK3, 1.8 V, up to 2 A RESET, pull low when VDIV lower than 1.23 V

This evaluation module is designed to provide access to the features of the TPS65261. Some modifications can be made to this module to test performance at different input and output voltages, current and switching frequency. Contact the TI Field Applications group for advice on these matters.

2 TPS65261 Schematic

Figure 1 shows the EVM schematic.

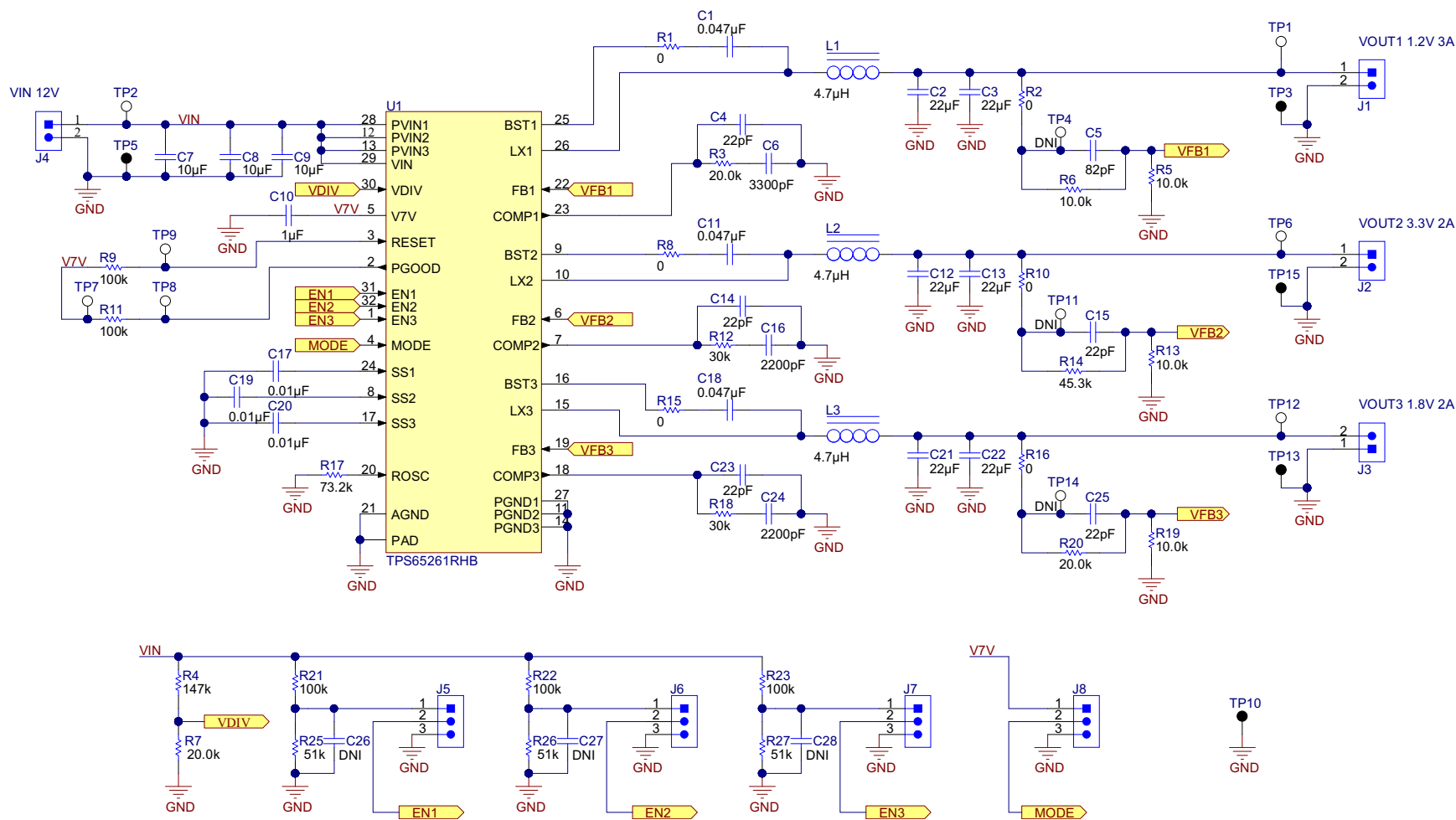


Figure 1. TPS65261 Schematic

3 Board Layout

Figure 2 illustrates the PCB layout for this EVM.

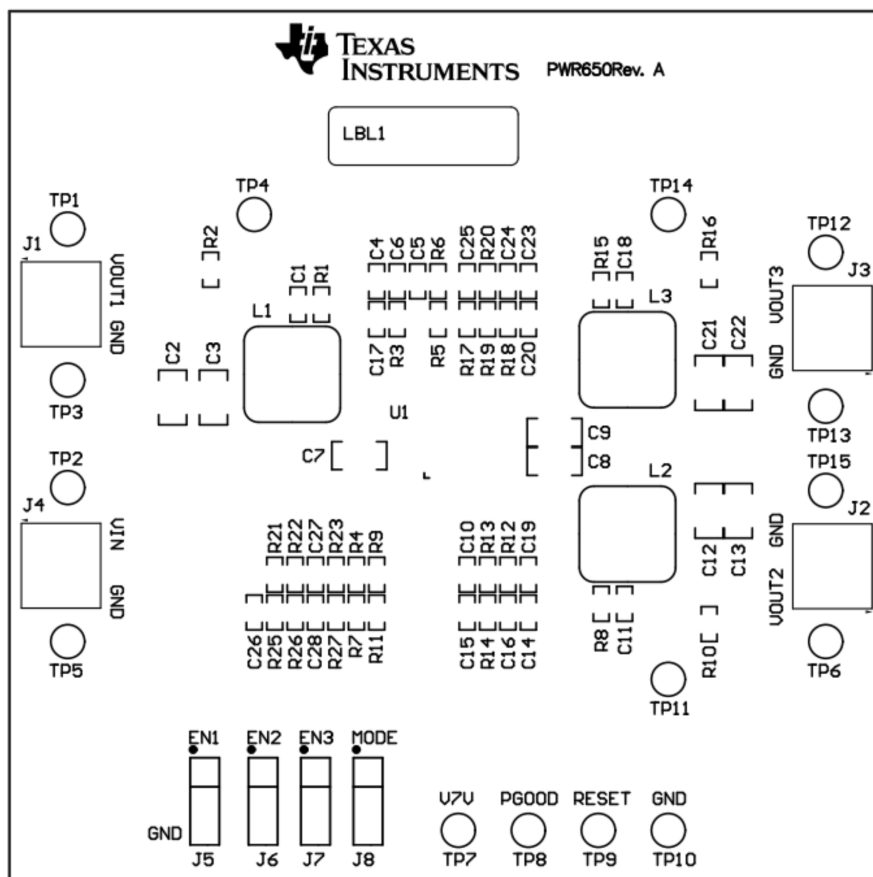


Figure 2. Component Placement (Top Layer)

3.1 EVM Layout

Figure 3 through Figure 6 illustrate the PCB layout for this EVM.

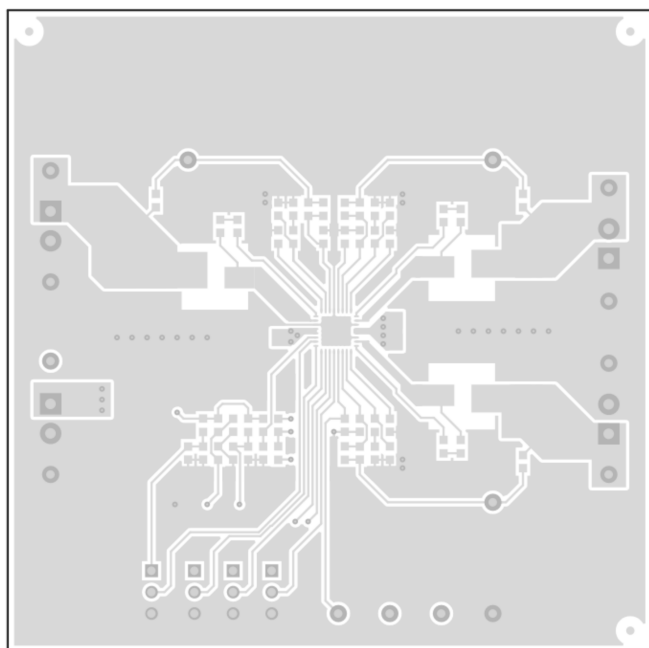


Figure 3. Board Layout (Top Layer)

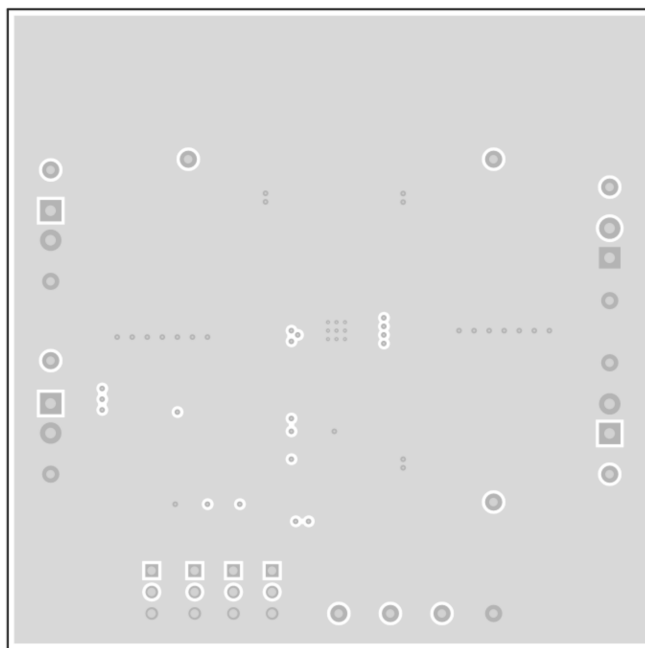


Figure 4. Board Layout (Second Layer)

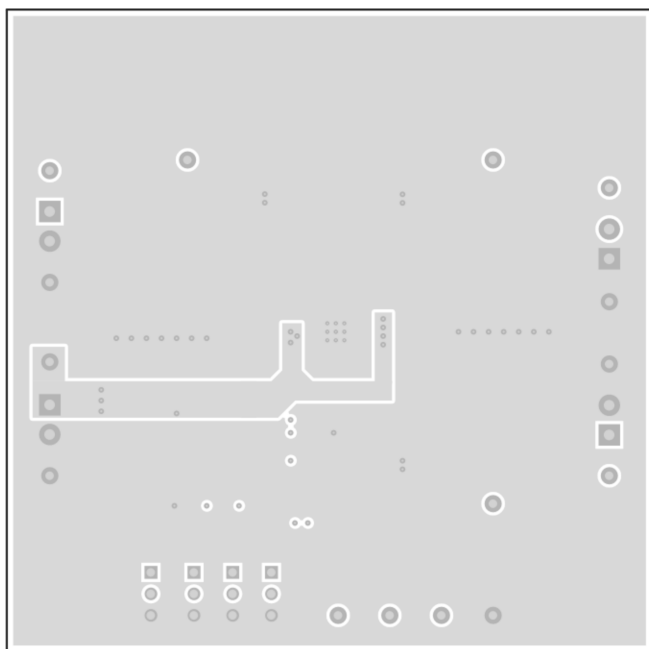


Figure 5. Board Layout (Third Layer)

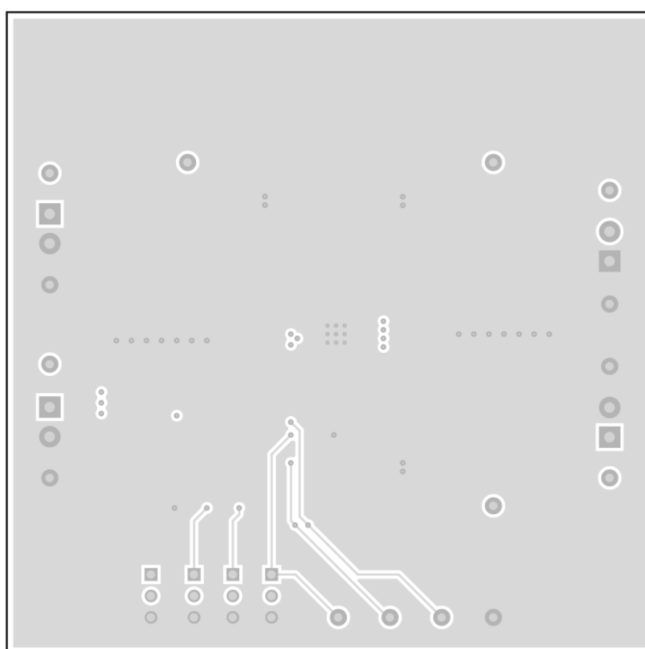


Figure 6. Board Layout (Bottom Layer)

4 Bench Test Setup Conditions

4.1 Headers Description and Jumper Placement

Figure 7 illustrates the header description and jumper placement on the EVM.

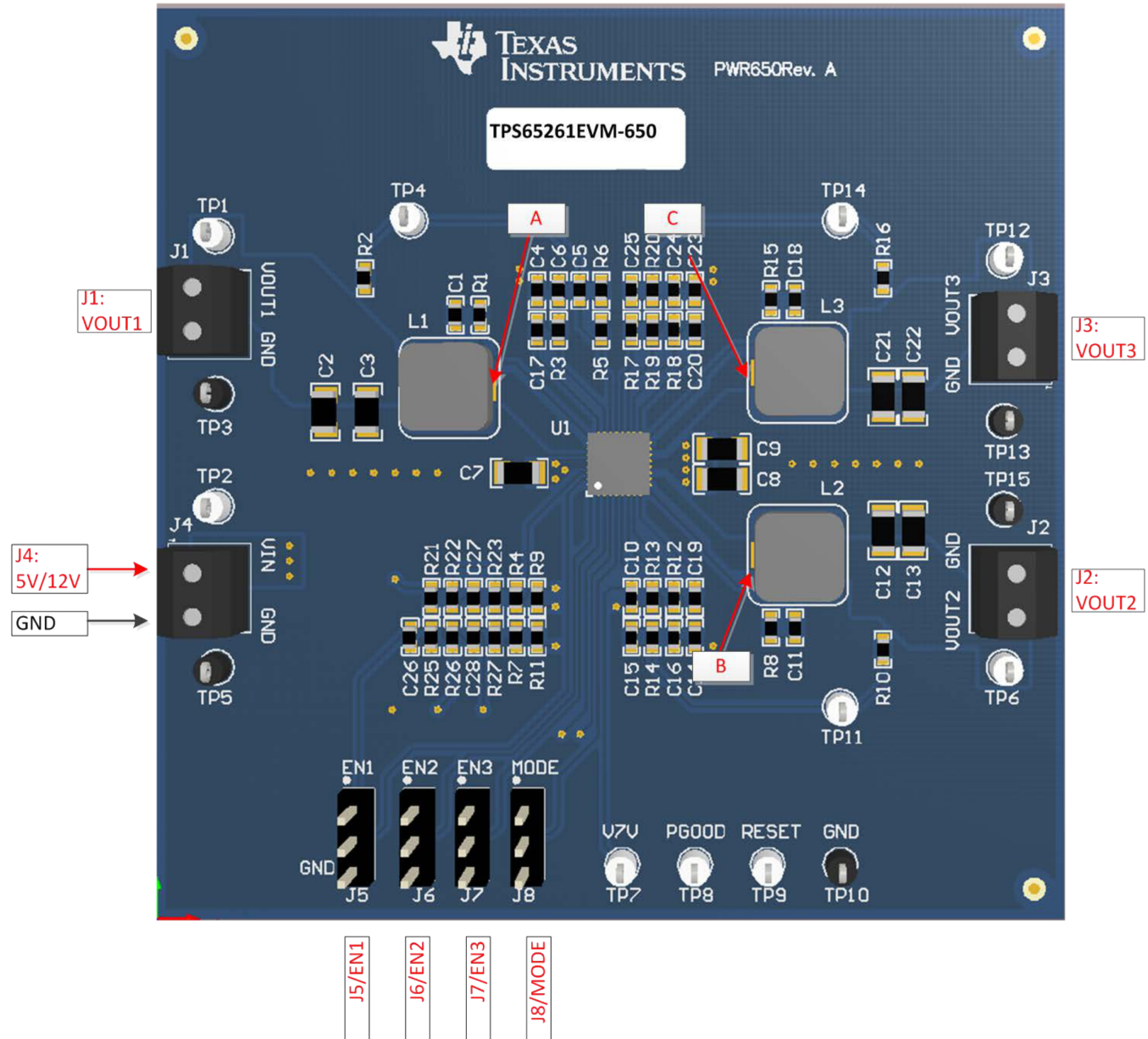


Figure 7. Header Descriptions and Jumper Placement

Test points:

A: LX of VOUT1

B: LX of VOUT2

C: LX of VOUT3

VOUT1, VOUT2, VOUT3, VIN, PGOOD, RESET, V7V

Table 2 lists the I/O connections.

Table 2. Input/Output Connection

Number	Function	Description
J1	BUCK1 connector	Output of BUCK1
J2	BUCK2 connector	Output of BUCK2
J3	BUCK3 connector	Output of BUCK3
J4	VIN connector	Apply power supply to this connector

4.2 Jumpers and Switches

Table 3 lists the jumpers on the EVM.

Table 3. Jumpers

Jumper	Function	Placement
J5	Buck1 enable (EN1)	Connect EN1 to GND to disable VOUT1, connect EN1 to VIN through a 100-kΩ resistor to enable VOUT1; leave open to enable VOUT1
J6	Buck2 enable (EN2)	Connect EN2 to GND to disable VOUT2, connect EN2 to VIN through a 100-kΩ resistor to enable VOUT2; leave open to enable VOUT2
J7	Buck3 enable (EN3)	Connect EN3 to GND to disable VOUT3, connect EN3 to VIN through a 100-kΩ resistor to enable VOUT3; leave open to enable VOUT3
J8	Mode	Power sequencing mode control pin. Connect this pin to GND to set power sequence with dedicated enable pin; connect this pin to V7V, set the power sequence with the pre-defined power up and power down sequence.

5 Power-Up Procedure

Power sequence with dedicated enable pin:

1. Connect J8 to GND
2. Apply 4.5 V - 18 V to J4
3. Toggle J5, J6, or J7 to enable VOUT1, VOUT2, and VOUT3, respectively
4. Apply loads to the output connectors

Power sequence with the pre-defined power up and power down sequence:

1. Connect J8 to V7V
2. Connect J5 to High (or Low), J6 to High (or Low)
3. Apply 4.5 V - 18 V to J4
4. Toggle J7 to enable VOUT1, VOUT2, and VOUT3
5. Apply loads to the output connectors.

6 Bill of Materials

Table 4 lists the BOM for this EVM.

Table 4. TPS65261 Bill of Materials

Designator	Qty	Value	Description	Package Reference	Part Number	Manufacturer
!PCB1	1		Printed Circuit Board		PWR650	Any
C1, C11, C18	3	0.047uF	CAP, CERM, 0.047uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H473K	TDK
C2, C3, C12, C13, C21, C22	6	22uF	CAP, CERM, 22uF, 16V, +/-20%, X5R, 1206	1206	1206YD226MAT2A	AVX
C4, C14, C15, C23, C25	5	22pF	CAP, CERM, 22pF, 50V, +/-5%, C0G/NP0, 0603	0603	06035A220JAT2A	AVX
C5	1	82pF	CAP, CERM, 82pF, 50V, +/-5%, C0G/NP0, 0603	0603	06035A820JAT2A	AVX
C6	1	3300pF	CAP, CERM, 3300pF, 50V, +/-10%, X7R, 0603	0603	C0603C332K5RACTU	Kemet
C7, C8, C9	3	10uF	CAP, CERM, 10uF, 25V, +/-10%, X5R, 1206	1206	GRM31CR61E106KA12L	MuRata
C10	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603	C1608X7R1E105K080AB	TDK
C16, C24	2	2200pF	CAP, CERM, 2200pF, 50V, +/-10%, X7R, 0603	0603	C0603C222K5RACTU	Kemet
C17, C19, C20	3	0.01uF	CAP, CERM, 0.01uF, 50V, +/-5%, X7R, 0603	0603	C0603C103J5RACTU	Kemet
C26, C27, C28	0	DNI	CAP, CERM, 0.01uF, 50V, +/-5%, X7R, 0603	0603	C0603C103J5RACTU	Kemet
J1, J2, J3, J4	4		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
J5, J6, J7, J8	4		Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin	PEC03SAAN	Sullins Connector Solutions
L1, L2, L3	3	4.7uH	Inductor, Shielded Drum Core, Superflux, 4.7uH, 6A, 0.02 ohm, SMD	WE-HC4	744311470	Würth Elektronik eiSos
LBL1	1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady
R1, R2, R8, R10, R15, R16	6	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	CRCW06030000Z0EA	Vishay-Dale
R3, R7, R20	3	20.0k	RES, 20.0k ohm, 1%, 0.1W, 0603	0603	CRCW060320K0FKEA	Vishay-Dale
R4	1	147k	RES, 147k ohm, 1%, 0.1W, 0603	0603	CRCW0603147KFKEA	Vishay-Dale
R5, R6, R13, R19	4	10.0k	RES, 10.0k ohm, 1%, 0.1W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale
R9, R11, R21, R22, R23	5	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
R12, R18	2	30k	RES, 30k ohm, 5%, 0.1W, 0603	0603	CRCW060330K0JNEA	Vishay-Dale
R14	1	45.3k	RES, 45.3k ohm, 1%, 0.1W, 0603	0603	CRCW060345K3FKEA	Vishay-Dale
R17	1	73.2k	RES, 73.2k ohm, 1%, 0.1W, 0603	0603	CRCW060373K2FKEA	Vishay-Dale
R25, R26, R27	3	51k	RES, 51k ohm, 5%, 0.1W, 0603	0603	CRCW060351K0JNEA	Vishay-Dale
SH-J1	1	1x2	Shunt, 100mil, Gold plated, Black	Shunt	969102-0000-DA	3M
TP1, TP2, TP6, TP7, TP8, TP9, TP12	7	White	Test Point, Miniature, White, TH	White Miniature Testpoint	5002	Keystone
TP3, TP5, TP10, TP13, TP15	5	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
TP4, TP11, TP14	0	DNI	Test Point, Miniature, White, TH	White Miniature Testpoint	5002	Keystone
U1	1		4.5V to 18V Input Voltage, 3A/2A/2A Output Current Triple Synchronous Step-Down Converter, RHB0032E	RHB0032E	TPS65261RHB	Texas Instruments
Note:		Unless otherwise noted in the columns, all parts may be substituted with equivalents.				

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